



SMD Comm X8G HT150C Flex, Ceramic, 9,100 pF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	20 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
Т	0.9mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

Т	0.9mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm
Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape

10000

Packaging Quantity

Specifications	
Capacitance	9,100 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute	- and
we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have	ive the
requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided	by us
with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.	•

© 2006 - 2025 YAGEO Generated 05/04/2025